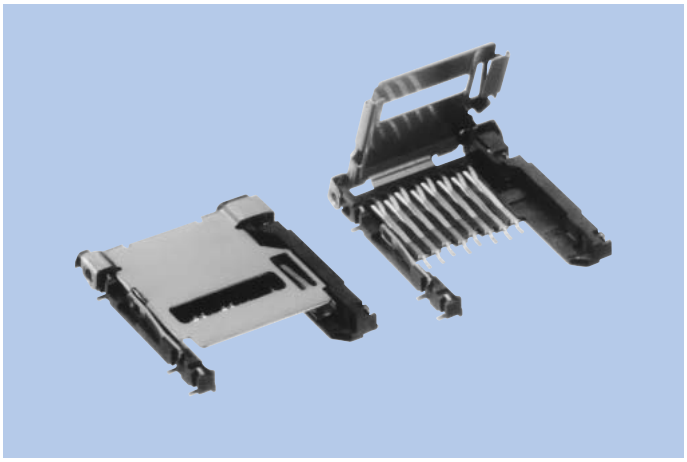
microSD card connectors
CIM-H33N

FEATURES

1. Hinge machanism type
2. Small and tin design
3. Prevents from losing card by attaching a card to the plate at card attachment and removal.
4. Card attachment and removal is easy by plate opening with spring force.
5. Contact slide on card pad at card setting with self-cleaning mechanism.
6. ESD countermeasure is possible at card attachment.



HOW TO ORDER

H33N	-	008	-	21	0	-	A	G	G	E
1		2		3	4		5	6	7	8

1 Series No. (H33N : Nomal type)
2 No. of contacts (008 : 8pins)
3 Housing material (21 : LCP resin)
4 Housing UL grade (0 : UL94V-0)
5 Contact plating (A : Gold)
6 Contact plating thickness (G : 3μm)
7 Contact read style (G : Angle SMT)
8 Package (E : Taping)

SPECIFICATIONS

ELECTRICAL CHARACTERISTICS

Rated Voltage	AC 50V (rms)
Rated Current	0.5A
Withstanding Voltage	500V AC (rms) 1minute
Insulation Resistance	1000MΩ min. (Initial value)
Contact Resistance	100mΩ max. (Initial value)

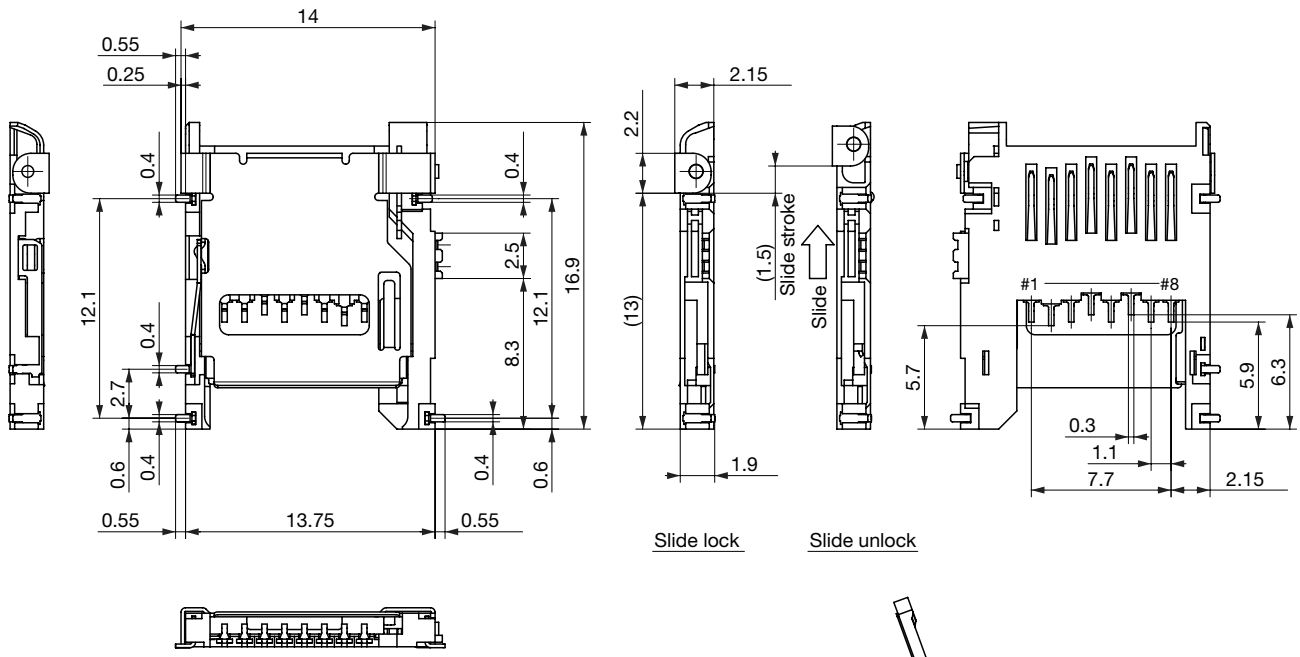
MECHANICAL CHARACTERISTICS

Life (Matching Cycle)	10,000times
Using Temperature Range	–25~+85°C

MATERIAL & FINISH

Component Parts	Material	Finish
Housing	LCP resin	(Black)
Contact	Copper Alloy	Gold plating
Plate	SUS	–
Lock Spring	Copper Alloy	Gold plating
Wing	Copper Alloy	Gold plating
Shaft	SUS	–
Torsion Spring	SUS	–

DIMENSIONS



Recommended PWB layout